# United States Patent Office

2,722,508
Patented Nov. 1, 1955

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#### 2,722,508

## ELECTRODEPOSITION OF ALLOYS CONTAINING COPPER AND TIN

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No Drawing. Application November 14, 1952, Serial No. 320,617

Claims priority, application Great Britain November 27, 1951

7 Claims. (Cl. 204-44)

The present invention relates to improvements in electroplating and is more particularly concerned with the electrodeposition of alloys containing copper and tin as the main constituents.

As is well known in bright chromium-plating techniques, the usual practice is to deposit a thin film of chromium 20 on an electrolytically-deposited under-coating of another metal, conveniently nickel. As an alternative which affords many technical advantages, the use of an alloy containing copper and tin as the main constituents in place of nickel has much to recommend it, but difficulties have hitherto been encountered in obtaining a satisfactory deposit under production conditions without undue complications. Thus the use of alloy anodes causes polarization and other difficulties and the necessary provision of separate copper and tin anodes, used either simultaneously in separate circuits or alternately, has meant added complications and cost.

The object of the present invention is to provide a process whereby an alloy containing copper and tin as the main constituents may be deposited on a cathode with no 35 more difficulty than is encountered in the electrodeposition of nickel or pure copper with substantially the same equipment.

According to the invention, the difficulties hitherto encountered in electro-depositing an alloy containing copper and tin as the main constituents, using anodes of the alloy in question, are overcome by including in the aqueous electrolyte an organic hydroxy acid, preferably citric acid, or a suitable salt thereof. When this is done, the alloy anodes dissolve in the bath in a steady and regular manner without any tendency to polarization or other disturbances. Moreover, the presence of citric acid or its compounds léads to a marked improvement in the appearance and texture of the deposited alloy.

An example of a suitable composition for the electrolyte is as follows:

#### Example 1

Gm.	./1.
Copper cyanide	40
Sodium stannate	20
Sodium cyanide (total)	65
Sodium hydroxide 7	11/2
Sodium citrate	50

This gives a rather weak electrolyte and in circumstances in which the use of a more concentrated electrolyte is preferable, the following composition might be used:

#### Example 2

			n./1.
Copper	cyanide		 20
Sodium	stannate		 100
Sodium	cyanide (tota	1) _	 35
Sodium	hydroxide	·	 10

The quantities of the various components may vary 70 within the ranges defined by the upper and lower limits set forth in the two preceding examples.

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For instance, the	proportions	by weight	of the	solids
may vary as follows	) <b>;</b>		4.5	4.77340

			Percent
	Copper	cyanide	525
;	Sodium	stannate	10-50
	Sodium	cyanide	10-35
	Sodium	hydroxide	3-5
	Sodium		10-45

Other suitable examples of electrolyte compositions are as follows:

#### Example 3

5		Preferred Concen- tration, g./l.	Percent- age Range, percent	Concentration Range, g./l.
20	copper carbonate	55 30 65 5 75	7-60 3-75 7-60 0. 25-20 3-70	20-80 10-50 20-80 1-20 25-125

#### Example 4

5		Preferred Concen- tration, g./l.	Percent- age Range, percent	Concentration Range, g./l.
)	copper oxide	15 100 45 100	3-50 3-50 8-70 10-80	10-50 10-50 20-100 25-125

#### Example 5

	Preferred Concen- tration, g./l.	Percent- age Range, percent	Concentration Range, g./l.
copper sulphite_sodium cyanide (total)_sodium stannate_potassium hydroxidecitric acid	50	7-50	20-80
	50	7-50	20-80
	60	3-40	10-50
	50	10-40	20-100
	50	10-40	20-100

The various components may be added to the aqueous bath separately or they may be mixed in suitable proportions beforehand and subsequently dissolved in the appropriate amount of water.

The composition of the anodes, which primarily controls the nature of the deposit, may be 80-95% copper and 5-20% tin and very good results have been obtained with 90% copper and 10% tin. It has also been found advantageous to include a small proportion of aluminum or aluminum alloy, for instance up to 2.5% of aluminum or up to 3% of an alloy of aluminum and magnesium.

It will be understood that although the deposit obtained according to the invention has been suggested as an undercoating for subsequent chromium plating, it can also be used as an independent finish or as a base for a further plating operation involving the deposit of other metals.

We claim:

- 1. A liquid for use as the electrolyte in an electrolytic bath for the deposition of a copper-tin alloy selected from the group consisting of an alloy of copper and tin, an alloy of copper, tin and up to 2.5% aluminum, and an alloy of copper, tin and up to 3% of an aluminum and magnesium alloy from anodes of the alloy to be deposited, said liquid composed of water, having dissolved therein 5-25% copper cyanide, 10-50% sodium stannate, 10-35% sodium cyanide, 3-5% sodium hydroxide and 10-45% sodium citrate.
  - 2. A composition adapted for use when dissolved in water as the electrolyte in an electrolytic bath for the deposition of a copper-tin alloy selected from the group

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consisting of an alloy of copper and tin, an alloy of copper, tin and up to 2.5% aluminum, and an alloy of copper, tin and up to 3% of an aluminum and magnesium alloy from anodes of the alloy to be deposited, said composition consisting of 5-25% copper cyanide, 10-50% sodium stannate, 10-35% sodium cyanide, 3-5% sodium hydroxide and 10-45% sodium citrate.

3. A process for the electrodeposition of a copper-tin alloy selected from the group consisting of an alloy of copper and tin, an alloy of copper, tin and up to 2.5% 10 aluminum, and an alloy of copper, tin and up to 3% of an aluminum and magnesium alloy on a cathode comprising passing an electric current through an aqueous electrolyte composed of water, 5-25% of a copper compound, 10-50% of an alkali-metal stannate, 10-35% of an alkali-metal cyanide and 10-50% of a compound having the citric acid radical selected from the group consisting of citric acid and an alkali-metal salt of citric acid,

and in which electrolyte the cathode and an anode of the alloy to be deposited are immersed.

4. A process as claimed in claim 3 in which the compound in the electrolyte is sodium citrate.

5. A process as claimed in claim 3 in which the compound in the electrolyte is an alkali-metal citrate.

6. A process as claimed in claim 3 in which the compound in the electrolyte is citric acid.

7. A process as claimed in claim 3 in which the com-10 position of the anode is 80-95% copper, 5-20% tin, 0-2.5% aluminum and 0-2% magnesium.

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